

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Currently amended) An optoelectronic component based on a surface mount technology, the optoelectronic component comprising:
 - an electrically conductive frame to form a base for an assembly;
 - an opaque plastic material to form a housing for the assembly;
 - a cavity formed within the plastic material;
 - at least one protrusion extending from a side surface of the housing to provide heat dissipation; and
 - at least one optoelectronic chip mounted in the cavity,
wherein the base protrudes from a middle portion to a bottom surface and two other side surfaces of the optoelectronic component, the bottom surface and the two other side surfaces of the optoelectronic component providing external mounting connection terminals.
2. (Previously presented) The optoelectronic component as claimed in claim 1, wherein the cavity is filled with a transparent or translucent resin material.
3. (Previously presented) The optoelectronic component as claimed in claim 1, wherein an electrical connection between the at least one optoelectronic chip and the base is provided by a metallic wire.

4. (Previously presented) The optoelectronic component as claimed in claim 1, wherein the external mounting connection terminals are provided for connecting to external sub-systems.

5. (Canceled)

6. (Previously presented) The optoelectronic component as claimed in claim 1, wherein the base protrudes outside the plastic material.

7-8. (Canceled)

9. (Previously presented) The optoelectronic component as claimed in claim 1, wherein the external mounting connection terminals are provided without any lead formations.

10. (Previously presented) An optoelectronic component based on a surface mount technology, the optoelectronic component comprising:

- an electrically conductive frame to form a base for an assembly;
- an opaque plastic material to form a housing for the assembly;
- a cavity formed within the plastic material;
- at least one protrusion extending from a side surface of the housing to provide heat dissipation; and
- at least one optoelectronic chip mounted in the cavity,

wherein the electrically conductive frame protrudes from a middle portion to two other side surfaces of the housing, the two other side surfaces of the housing providing external mounting connection terminals.

11. (Previously presented) The optoelectronic component as claimed in claim 10, wherein the cavity is filled with a transparent or translucent resin material.

12. (Previously presented) The optoelectronic component as claimed in claim 10, wherein the external mounting connection terminals are provided without any lead formations.

13. (Previously presented) The optoelectronic component as claimed in claim 10, wherein an electrical connection between the at least one optoelectronic chip and the base is provided by a metallic wire.

14. (Previously presented) The optoelectronic component as claimed in claim 10, wherein the external mounting connection terminals are provided for connecting to external sub-systems such as PCBs.